

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0	2.0	0.02
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.03
	Lead alloy	Lead (Pb)	7439-92-1	0.07	95.5	1.1
Subtotal				0.07	100	1.15
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.06	100.0	1.02
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.22
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01	0.03	0.22
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.1	0.72
	Copper alloy	Copper (Cu)	7440-50-8	43.27	99.84	715.85
Subtotal				43.33	100	717.01
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.2	4.0	36.4
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	8.25	15.0	136.5
	Filler	Silica fused	60676-86-0	40.7	74.0	673.4
	Flame retardant	Metal hydroxide		3.85	7.0	63.7
Subtotal				55	100	910
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.51	100.0	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02	100.0	0.3
Total				99.99	100	1654.48

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